



Standardization Support for the upcoming EU semiconductor manufacturing industry

CEN/CENELEC

About me



- ❑ **José Manuel Pulido:**
- ❑ Lead Cybersecurity Consultant and Senior Cybersecurity Evaluator at jtsec
- ❑ Common Criteria expert
- ❑ CCToolbox developer
- ❑ More than 10 years of experience in cybersecurity technologies
- ❑ Speaker at several conferences including ICC20, ICC21 and ICC22

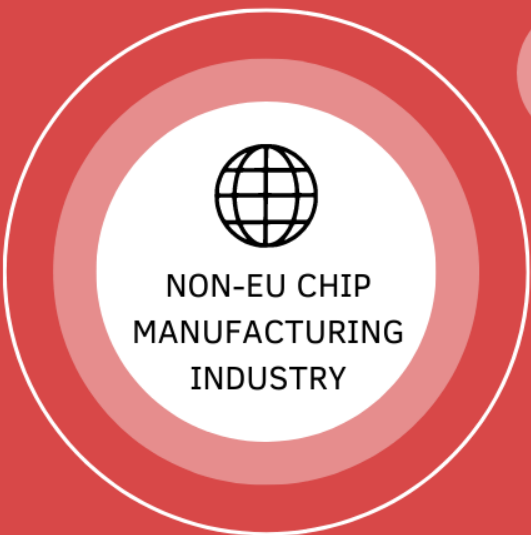
About us



- ❑ Cybersecurity **evaluation** & consultancy **services**
- ❑ Common Criteria, LINCE, IEC 62443-4-1 , IEC 62443-4-2 and ETSI EN 303 645 accredited lab.
- ❑ **Highly Involved in standardization** activities (ISO, CEN/CENELEC, ISCI WGs, ENISA CSA WGs, CCUF, ERNCIP, ...)
 - ❑ Editors of FITCEM, LINCE or ISO/IEC TS 9569 Patch Management
- ❑ Members of the SCCG (Stakeholder Cybersecurity Certification Group)

Landscape and motivation – EU Chips Act

- ❑ Cybersecurity standards for ICT products are aligned with and can support EU Chips Act objectives



Exponential demand of chips across different industries



High dependency with non-EU countries for chip production



Low resilience of the supply chain to crisis events



Compliance of production processes with EU regulations



Security improvement of the supply chain



Mitigate the impact of crisis in chip-based industry

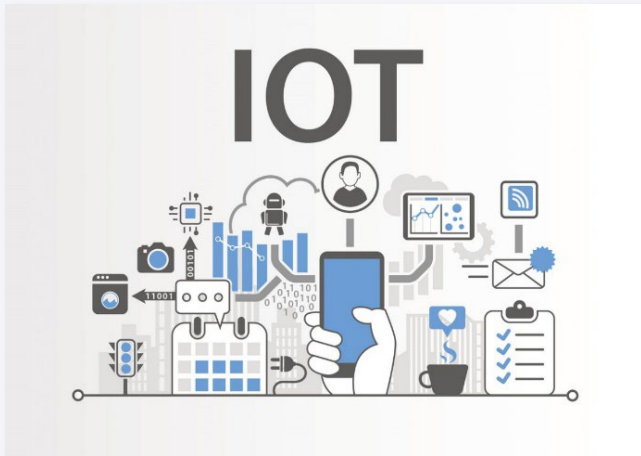
Security standardization needs in chip-based products

Security ICs and Smartcards



- Payment industry.
- National IDs, passports.
- Mobile wallets.
- **High** assurance security certifications required

IoT and general-purpose Devices



- Always connected devices.
- Breaches could compromise home and corporate networks.
- **Medium-Low** assurance security certifications required.



Security standards for chip-based products shall provide security assurance on:

- Security specifications
- Functional security testing
- Vulnerability analysis and penetration testing
- Security user guidance.
- Development and lifecycle assurance, which includes **chip design and manufacturing security assessment.**

EU Cybersecurity standards for chip-based products

Common Criteria

- Low, medium and high assurance. Best-suited for high.
- Specific assurance and methodologies for Security ICs.
- Assurance evaluation of the production and supply chain lifecycle.

EUCC

- Low, medium and high assurance.
- Reuses all assurance levels from Common Criteria, without site security

FITCEM (EN 17640)

- Modular framework adaptable to different assurance needs.
- Meant to replace national standards in Europe (LINCE, BSZ, BSPA, CSPN)
- Fixed time evaluation.

SESIP

- Specific for IoT platforms – Vertical standard
- Supports low, medium and high assurance.
- High assurance evaluations require a previous CC evaluations.

ETSI EN 303 645

- Designed for consumer IoT devices.
- No high assurance evaluations.
- Focused on functional security requirements and provisioning.



Addresses security of chip production in design and manufacturing centers.



Audits to development and production centers included in evaluations



Production lifecycle security to be addressed in next version of the standard (under development)

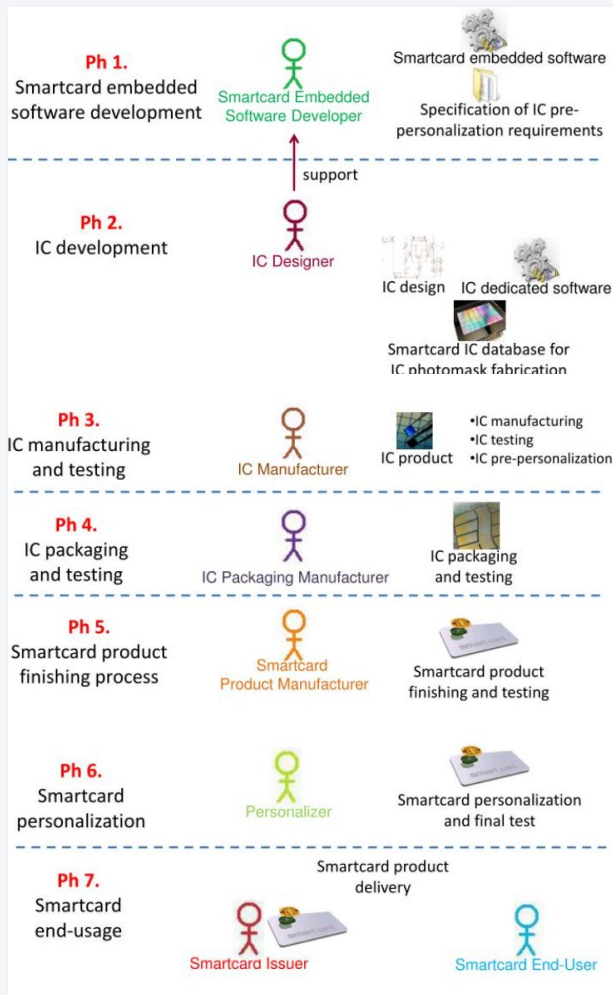


Security of chip production only addressed through CC



Chip lifecycle and production not assessed

Lifecycle of high-assurance semiconductors



- IC Developers perform:
 - Design of IC circuit.
 - IC FW development
 - IC SW development
 - IC Unit-testing
 - IC logical testing
 - Design of test program for fabs
 - Design personalization program
 - Monitoring /handling of fab testing output

- Fabs/SATs perform:
 - Manufacturing
 - Packaging
 - Finishing and execution of volume testing

- Pre-personalization usually performed in SATs at large-volume scale

- Huge share of EU vendors
- Decision making in all critical aspects of the device
- **Decision making and talent are based in EU**
- **EU countries are leaders and pioneers in IC industry**

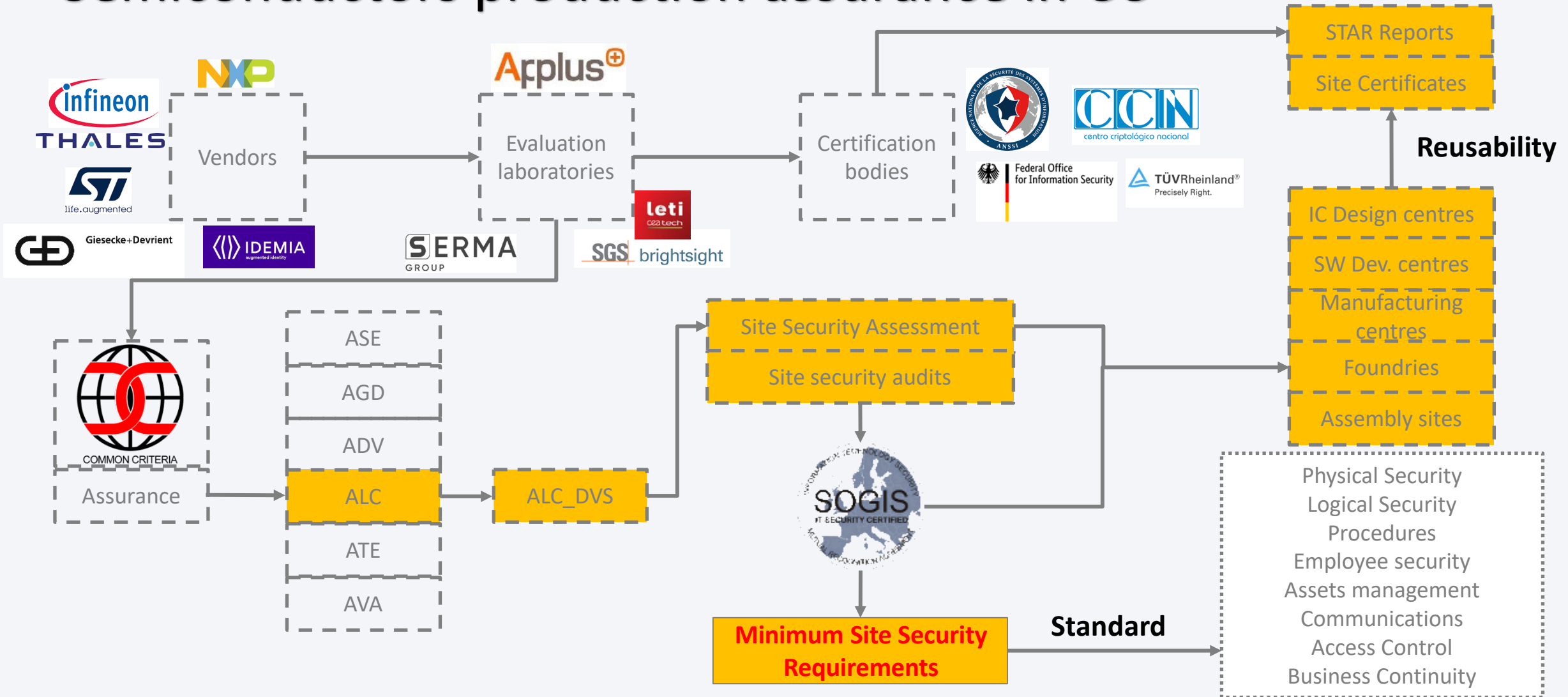


- Mostly outside EU (Asia)
- Manufacture ICs designed mainly in EU
- Run test & QA programs designed at EU with no decision making
- Requires specialized equipment and facilities



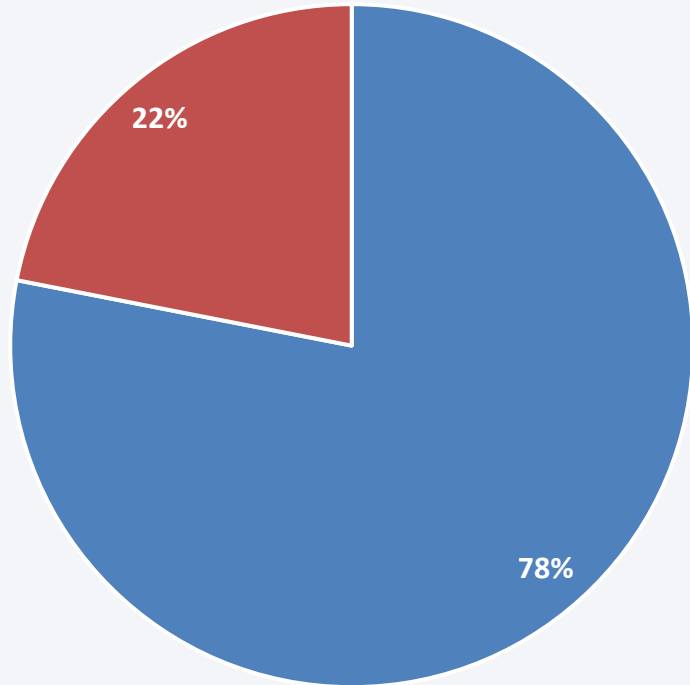
- **EU has the tradition and talent but lacks manufacturing centers to control the full production loop**

Semiconductors production assurance in CC



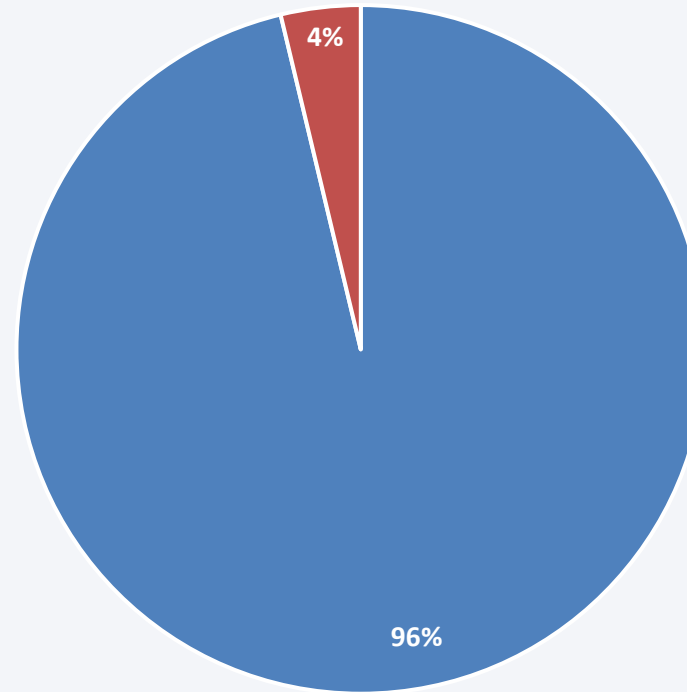
Security ICs evaluation share in EU (5 years - CC)

Vendors of certified Security ICs



■ EU vendors ■ Non-EU vendors

Security IC evaluations in Europe



■ EU Countries ■ Non-EU Countries

Lifecycle assessment in certifications without high assurance

Security certifications without High assurance needs

Lifecycle security assessment

Swift and cost-effective.

Useful when no high security needs.

Suitable for consumer IoT and general-purpose devices.

Security in development and production is not addressed.

Lack of control on development and production environments could result in:

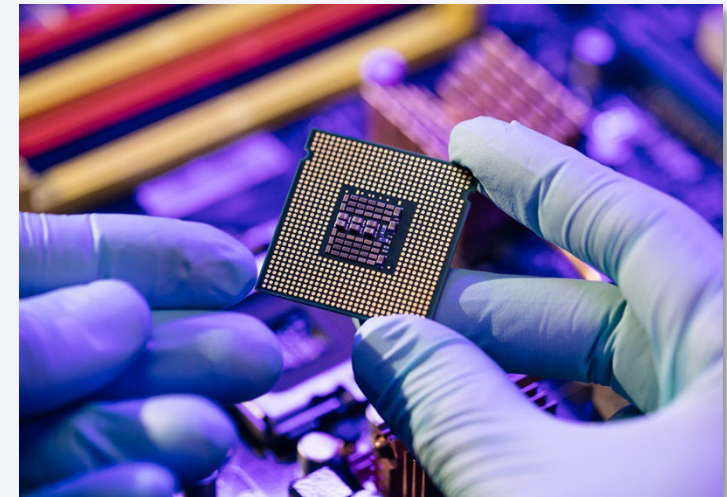
- Sensitive information leaks.
- Introduction of vulnerabilities

- ETSI EN 303 645
- FITCEM Basic
- CC/SESIP under EAL3
- EUCC below High

- ❑ There is no ad-hoc methodology addressing production and lifecycle security in certifications without high-assurance needs.
- ❑ Options to fill this gap:
 - Mandatory life cycle evaluation as a requirement to produce semiconductors undergoing security evaluations. (e.g. ISO/IEC 27001).
 - Ad-hoc lightweight standard that considers life cycle evaluation in a cost-effective way, supporting reusability
 - Currently being worked in FITCEM
- ❑ Solutions shouldn't affect cost and speed, and should support reusability.

Standards are ready to support EU semiconductors industry

- ❑ Horizontal standards (CC, EUCC, FITCEM) are ready to cover all sectorial domains that use semiconductors.
- ❑ Vertical standards such as SESIP (IoT platforms) and ETSI EN 303 645 (Consumer IoT) cannot not be taken as a to-go option for all sectorial domains.
- ❑ High assurance standards (CC, MSSR) already consider the whole lifecycle security, including manufacturing centers.
- ❑ Evaluations without high assurance needs, don't cover lifecycle and production security. It needs to be defined if it will be a requirement for the future market.



ETSI EN 303 645 V2.1.1 (2020-06)



SESIP™

Industry is ready to support EU semiconductor production

EU vendors:

- Are semiconductors market leaders.
- Have a long tradition in semiconductors industry.
- Have massive talent and expertise in the field.



EU schemes and laboratories:

- Have almost whole world-market share in Security ICs.
- Have massive experience auditing manufacturing sites in the context of security evaluations.
- Have historically contributed to enhance security in non-EU manufacturers.

EU **standards, vendors, schemes and labs** will be a cornerstone in the transition to EU semiconductor manufacturing companies.

- They will greatly contribute to improve security, monitoring and regulation compliance in semiconductor production.
- They will support to create resilience to supply chain disruptions.

Contact

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**“Any fool can make something complicated. It takes a
genius to make it simple.”
Woody Guthrie**